

# P-Channel 8 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)	
- 8	0.122 at V <sub>GS</sub> = - 4.5 V	1.2		
	0.141 at V <sub>GS</sub> = - 2.5 V	1.1	5.91	
	0.168 at V <sub>GS</sub> = - 1.8 V	0.60	5.91	
	0.198 at V <sub>GS</sub> = - 1.5 V	0.50		

## **FEATURES**

 Halogen-free According to IEC 61249-2-21 Definition

Compliant to RoHS Directive 2002/95/EC

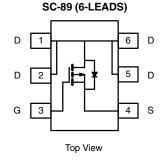
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>q</sub> Tested

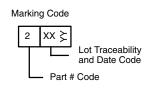


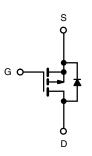
ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

• Load Switch for Portable Applications







Ordering Information: Si1051X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	(T <sub>A</sub> = 25 °C, unle	ess otherwise no	oted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 8	V	
Gate-Source Voltage		V <sub>GS</sub>	± 5		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	,	1.2 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	I <sub>D</sub>	0.97 <sup>b, c</sup>	А	
Pulsed Drain Current		I <sub>DM</sub>	- 8		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	0.2 <sup>b, c</sup>	А	
M ·	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.236 <sup>b, c</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C		0.151 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian una lumation de Analeianth d	t ≤ 5 s	B	440	530	°C/W
Maximum Junction-to-Ambient <sup>b, d</sup>	Steady State	R <sub>thJA</sub>	540	650	

### Notes:

- a. Based on  $T_A = 25$  °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 650 °C/W.

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<b>SPECIFICATIONS</b> ( $T_J = 25$ °C)  Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	• • • • • • • • • • • • • • • • • • • •	1001 0 0 1101110110		7			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 8			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 6.19			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	– I <sub>D</sub> = - 250 μA		2.13		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.3		- 1	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -8 V, V <sub>GS</sub> = 0 V			- 1	nA	
		V <sub>DS</sub> = -8 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C			- 10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 8			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.2 A		0.091	0.122		
	D	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1.1A		0.106	0.141	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.60 A		0.117	0.168		
		V <sub>GS</sub> = - 1.5 V, I <sub>D</sub> = - 0.50 A		0.129	0.198		
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = - 4 V, I <sub>D</sub> = - 1.2 A		4.93		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			560		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -4 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180			
Reverse Transfer Capacitance	C <sub>rss</sub>			112			
Total Cata Chausa	0	V <sub>DS</sub> = - 4 V, V <sub>GS</sub> = - 5 V, I <sub>D</sub> = - 1.2 A	6.3 9.4	9.45			
Total Gate Charge	$Q_g$			5.91	8.87	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -4 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.2 \text{ A}$		1.98			
Gate-Drain Charge	$Q_{gd}$			1.25			
Gate Resistance	$R_g$	f = 1 MHz		9.8	14.7	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			7.2	10.8		
Rise Time	t <sub>r</sub>	$V_{DD} = -4 \text{ V}, R_{L} = 4.16 \Omega$		36	54	ns	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -0.96 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		52	78		
Fall Time	t <sub>f</sub>			16	24		
<b>Drain-Source Body Diode Characteris</b>	tics						
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 8	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 1.0 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			18.8	28.2	nC	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = - 1.0 A, dl/dt = 100 A/μs		4.7	7.05		
Reverse Recovery Fall Time	t <sub>a</sub>			15		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			3.8			

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

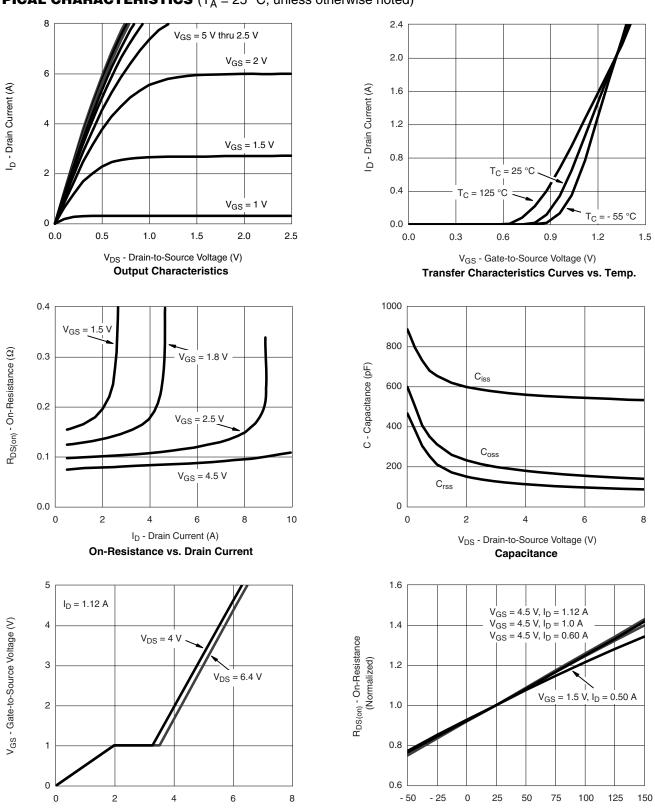
b. Guaranteed by design, not subject to production testing.







## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



Q<sub>g</sub> - Total Gate Charge (nC)

**Gate Charge** 

T<sub>J</sub> - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

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0.5

0.4

0.3

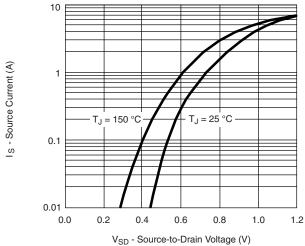
0.2

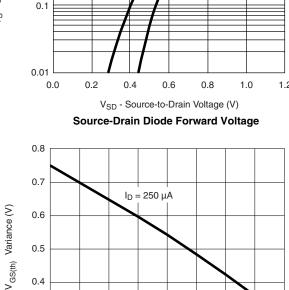
- 50

- 25

0

# **TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}\text{C}$ , unless otherwise noted)



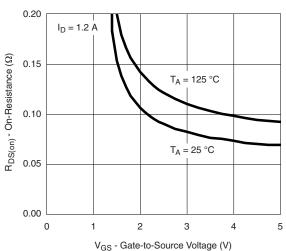


50 75 T<sub>J</sub> - Temperature (°C) **Threshold Voltage** 

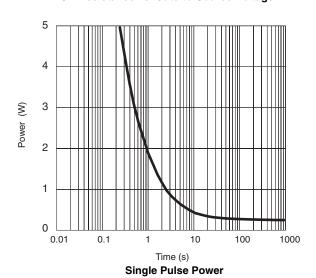
100

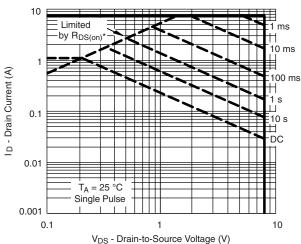
125

150



On-Resistance vs. Gate-to-Source Voltage





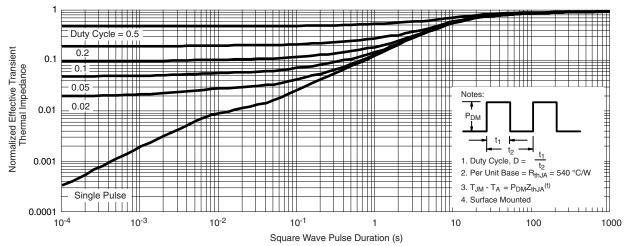
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient





## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

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